

# **MXD8530**

SP3T Switch for 0.1~3G Application

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#### **General Description**

The MXD8530 is a Single Pole, Triple-Throw (SP3T) antenna switch. The high linearity performance and low insertion loss achieved by the MXD8530 make it an ideal choice for main/diversity switching commonly used in LTE-based handsets, data cards, and tablets that use antenna diversity solutions. The symmetric port designs provide flexibility in signal routing for both receive diversity and higher power WCDMA/FDD, and WLANs transmit/receive applications.

Switching is controlled by two CMOS/TTL-compatible control voltage inputs (V1 and V2). Depending on the logic voltage level applied to the control pins, the ANT pin is connected to one of five switched RF outputs (RF1 to RF2) using a low insertion loss path, while the paths between the ANT pin and the other RF pins are in a high isolation state. No external blocking capacitors are

required on the RF paths unless VDC is externally applied.

The MXD8530 is manufactured in a compact, 12-pin 2.0 x 2.0 mm, Quad Flat No-Lead (QFN) package. A functional block diagram is shown in Figure 1. The pin configuration and package are shown in Figure 2. Signal pin assignments and functional pin descriptions are provided in Table 1.

#### **Applications**

- WCDMA band and mode switching
- Antenna switch for multimode systems
- 802.11 b/g/n WLANs

#### **Features**

- Broadband frequency range: 0.1 to 3.0 GHz
- Low insertion loss: 0.45 dB typical @ 2.5 GHz
- High isolation: >30 dB @ 2.5 GHz
- No external DC blocking capacitors requires
- Small QFN (12-pin, 2.0 x 2.0 mm) package

### **Functional Block Diagram and Pin Function**

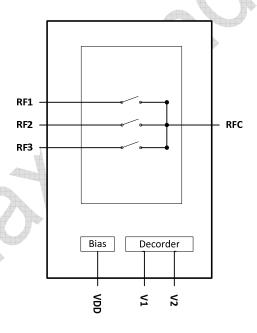


Figure 1. Functional Block Diagram

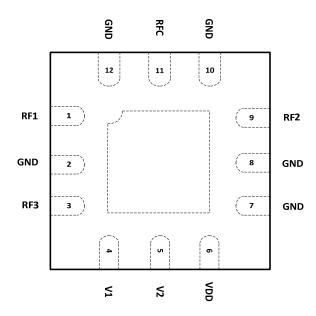


Figure 2. Pin Diagram



## **Application Circuit**

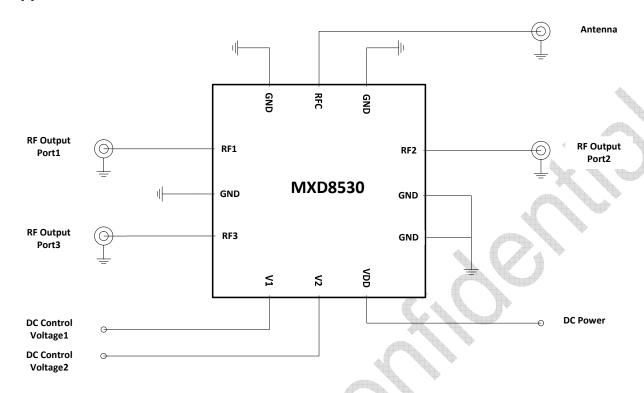


Figure 3. MXD8530 Evaluation Board Schematic

**Table 1. Pin Description** 

Pin No.	Name	Description	Pin No.	Name	Description
1	RF1	RF I/O path 1	7	GND	Ground
2	GND	Ground	8	GND	Ground
3	RF3	RF I/O path 3	9	RF2	RF I/O path 2
4	V1	DC control voltage 1	10	GND	Ground
5	V2	DC control voltage 2	11	RFC	RF common port
6	VDD	DC supply	12	GND	Ground

Note: Bottom ground paddles must be connected to ground.

**Table 2. Truth Table** 

Control	pins	Switched RF Outputs				
V1	V2	RF1	RF2	RF3		
0	0		Shutdown			
0	1	Insertion Loss	Insertion Loss Isolation Isolation			
1	0	Isolation	Insertion Loss	Isolation		
1 1 1 1 2	1 1 Isolation		Isolation Insertion Loss			

**Note:** "1" = 1.0 V to 3.30 V. "0" = 0 V to +0.3 V.

# **Recommended Operation Range**

Table 3.

Parameters	Symbol	Min	Тур	Max	Units
Operation Frequency	f1	0.1	-	3.0	GHz
Power supply	VDD	2.0	2.8	3.0	V
Switch Control Voltage (H)	V <sub>H</sub>	1.0	1.8	3.0	V
Switch Control Voltage (L)	$V_L$	0	0	0.3	V

## **Specifications**

## **Table 4. Electrical Specifications**

Danamatan	Comple al	Specification			l lusit a	Test Condition	
Parameter	Symbol	Min.	Min. Typical Max.		Units	(Note 2)	
DC Specifications							
Supply voltage	VDD	2.0	2.8	3.0	V		
Supply current	IDD		83		μΑ		
Control current	ICTL		2		μΑ	VCTL = 1.8 V	
Shutdown mode supply current	IOFF		5		μΑ	V1/2/3 = 1.8 V, VDD = 3 V	
Turn-on switching time	Ton	2 μs voltag power		50% of final control voltage to 90% of final RF power, switching between RF1/2/3			
RF Specifications		•		40000			
Insertion loss (RFC pin to			0.35	0.40	dB	0.8 to 1.0 GHz	
RF1/2/3 pins)	IL		0.40	0.50	dB	1.0 to 2.2 GHz	
			0.45	0.55	dB	2.2 to 3.0 GHz	
Isolation (RFC pin to		38	45	7	dB	0.8 to 1.0 GHz	
RF1/2/3 pins)	ISO	29	36		dB	1.0 to 2.2 GHz	
		26	33		dB	2.2 to 3.0 GHz	
Input return loss (RFC pin to RF1/2/3 pins)	RL		-20		dB	0.8 to 3.0 GHz	
Second harmonics (RFC pin to RF1/2/3 pins)	2fo		+85		dBc	PIN = +20 dBm, 0.1 to 3.0 GHz	
Third harmonics (RFC pin to RF1/2/3 pins)	3fo		+85		dBc	PIN = +20 dBm, 0.1 to 3.0 GHz	
0.1 dB Compression Point		0.1 GHz to 3 GHz					
3rd Order Input Intercept		dBm	@ 3.0 GHz, PIN = +20 dBm, Δf = 1 MHz				

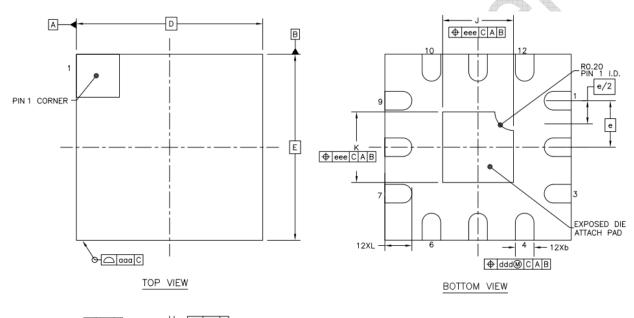
## **Absolute Maximum Ratings**

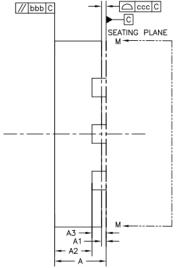
**Table 5. Maximum ratings** 

Parameters	Symbol	Minimum	Maximum	Units
Supply voltage	$V_{DD}$	+2.5	+3.0	V
Control voltage (V1 and V2)	$V_{CTL}$	-0.5	+3.0	V
RF input power (RF1 to RF3)	P <sub>IN</sub>		+36	dBm
Operating temperature	T <sub>OP</sub>	-40	+85	°C
Storage temperature	T <sub>STG</sub>	-55	+150	°C
Human Body Mode	HBM		1000	V
Machine Mode	MM		100	V
Charged Device Mode	CDM		500	V

Note: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device

## **Package Outline Dimension**





DESCRIPTION		SYMBOL	MILLIMETER			
		STIMBOL	MIN	NOM	MAX	
TOTAL THICKNESS		A	0.50	0.55	0.60	
STAND OFF		A1	0.00		0.05	
MOLD THICKNESS		A2	0.35	0.40	0.45	
L/F THICKNESS		A3	0.147	0.152	0.157	
LEAD WIDTH	b	0.15	0.20	0.25		
BODY SIZE	X	D	1.95	2.00	2.05	
BODT SIZE	Υ	E	1.95	2.00	2.05	
LEAD PITCH		е	0.50 BSC			
EP SIZE	X	J	0.71	0.76	0.81	
EP SIZE	Υ	К	0.71	0.76	0.81	
LEAD LENGTH	L	0.24	0.29	0.34		
PACKAGE EDGE TOLER	aaa	0.05				
MOLD FLATNESS	bbb	0.05				
COPLANARITY	ccc	0.05				
LEAD OFFSET	ddd	0.1				
EXPOSED PAD OFFSET	eee	0.1				

Figure 4. package outline dimension

#### **Reflow Chart**

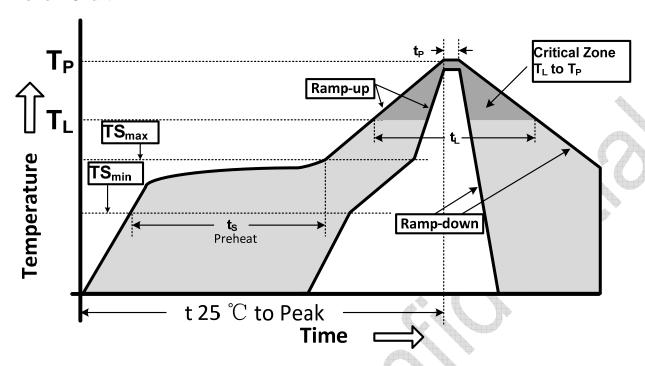


Figure 5. Recommended Lead-Free Reflow Profile

Table 6.

Profile Parameter	Lead-Free Assembly, Convection, IR/Convection			
Ramp-up rate (TS <sub>max</sub> to T <sub>p</sub> )	3°C/second max.			
Preheat temperature (TS <sub>min</sub> to TS <sub>max</sub> )	150℃ to 200℃			
Preheat time (t <sub>s</sub> )	60 - 180 seconds			
Time above TL , 217℃ (t <sub>L</sub> )	60 - 150 seconds			
Peak temperature (T <sub>p</sub> )	260℃			
Time within 5°C of peak temperature(t <sub>p</sub> )	20 - 40 seconds			
Ramp-down rate	6℃/second max.			
Time 25°C to peak temperature	8 minutes max.			

#### **ESD Sensitivity**

Integrated circuits are ESD sensitive and can be damaged by static electric charge. Proper ESD protection techniques should be used when handling these devices.

#### **RoHS Compliant**

This product does not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE), and are considered RoHS compliant.

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